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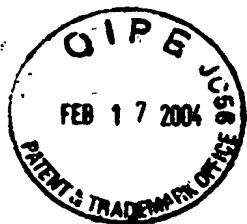
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1303.39636X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: I. WATANABE, et al.
Application No: 09/762,823
Filed: April 23, 2001
Title: ADHESIVE FOR BONDING CIRCUIT MEMBERS, CIRCUIT BOARD AND PROCESS FOR ITS PRODUCTION
Group: 1714
Examiner: Edward J. CAIN

DECLARATION UNDER 37 C.F.R. §1.132

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We, Itsuo WATANABE, Kenzo TAKEMURA, Akira NAGAI, Kazuhiro ISAKA, Osamu WATANABE and Kazuyoshi KOJIMA, each a citizen of Japan, presently residing respectively at 1194-6, Ipponmatsu, Shimodate-shi, Ibaraki-ken, 308-0842, Japan; 8237-1, Yuki, Yuki-shi, Ibaraki-ken, 307-0001, Japan; 2-20-11, Matsushiro, Tsukuba-shi, Ibaraki-ken, 305-0035, Japan; 901 N. Pollard Street, Apt. #1705, Arlington, VA 22203; 107 Espoir kawashima, 1453-1, Ogawa, Shimodate-shi, Ibaraki-ken, 308-0857, Japan; and A-201 Sanfiria sakae, 6381-15, Yuki, Yuki-shi, Ibaraki-ken, 307-0001, Japan, DECLARE THAT:

1. We are the named inventors of the subject matter disclosed and claimed in Application No. 09/762,823, filed April 23, 2001 (hereinafter above-identified application).

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2. We are aware of the Office Action mailed July 28, 2003 in the above-identified application, and the rejection of claims 1-21 and 32 therein under 35 U.S.C. §102(a) as anticipated by the teachings of International (PCT) Publication Application No. W098/03047, published January 22, 1998 (hereinafter WO '047); and the statement in the Office Action mailed July 28, 2003, in the above-identified application that this rejection is maintained substantially as set forth in the previous Office Action with the exception that the international priority document to the U.S. reference is cited.
3. We are also aware of the Office Action mailed January 21, 2003 (that is, the previous Office Action to the Office Action mailed July 28, 2003), in the above-identified application, rejecting claims under 35 U.S.C. §102(e) as anticipated by the teachings of U.S. Patent No. 6,328,844 to Watanabe, et al. (hereinafter Watanabe, et al.), and are also aware that Watanabe, et al. is the U.S. reference corresponding to WO '047.
4. We are further aware of the statements in the second paragraph of Item 8 on page 3 of the Office Action mailed January 21, 2003, in the above-identified application, that Watanabe, et al. discloses adhesive compositions comprising both insulative and conductive fillers, reference being made to column 4, line 22 to column 5, line 3; discloses that the adhesive has a modulus of elasticity of between 100 and 2,000 MPa at 40°C; and discloses that the inorganic fillers are present in amounts at least greatly overlapping amounts in the claims of the above-identified application that were rejected over Watanabe, et al.

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5. Insofar as the disclosure in Watanabe, et al., including the description in column 4, line 22 to column 5, line 3, and corresponding disclosure in WO '047, describes the subject matter of claims 1-21 and 32 of the above-identified application, this disclosure describes inventions by inventors named in the above-identified application, and not inventions of inventors named in Watanabe, et al. and WO '047 and not named as inventors in the above-identified application.

6. We, as the inventors of subject matter disclosed in Watanabe, et al. and in WO '047 that describes the invention set forth in claims 1-21 and 32 of the above-identified application, disclosed this subject matter to the inventors named in Watanabe, et al. and in WO '047.

7. The inventorship of the subject matter claimed in claims 1-21 and 32 of the above-identified application is correct in that Watanabe, et al. and WO '047 include subject matter disclosed to the inventors named in Watanabe, et al. and in WO '047, and not named as inventors in the above-identified application, by inventors named in the above-identified application.

01/20/2004 2月 2日 15時34分 02987日立化成 五所官 開発部

▲ ヒタチカセイ(ツクハ)チテキシヨウク

NO. 7319

PP. 20/010

01/20/2004 1月29日 13時54分

SOEI PATENT & LAW FIRM

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Feb. 2, 2004

Date

Itsumi Watanabe

ITSUMI WATANABE

Feb. 7, 2004

Date

Kenryo Takemura

KENRYO TAKEMURA

Feb. 2, 2004

Date

Akira Nagai

AKIRA NAGAI

Feb. 11, 2004

Date

Kazuhiko Isaka

KAZUHIRO ISAKA

Feb. 2, 2004

Date

Osamu Watanabe

OSAMU WATANABE

Feb. 2, 2004

Date

Kazuyoshi Kojima

KAZUYOSHI KOJIMA